

Description

The DFI450HF12I4ME7 is a Half Bridge IGBT Power Module. It integrates high performance IGBT chips designed for the applications such as High Power Switching supply and Motor control.



Features

- Blocking voltage:1200V
- Low saturation voltage $V_{CE(sat)}$
- Low Switching Losses
- Thermistor inside

Applications

- High Power Switching Applications
- Motor Drives
- Solar inverter Systems
- Uninterrupted Power Supply

Circuit diagram

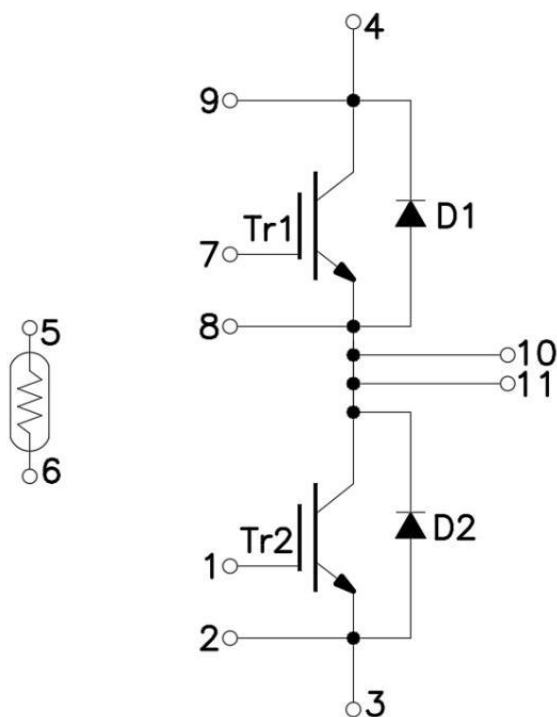


Figure 1. Out drawing & circuit diagram for DFI450HF12I4ME7

Pin Configuration and Marking Information

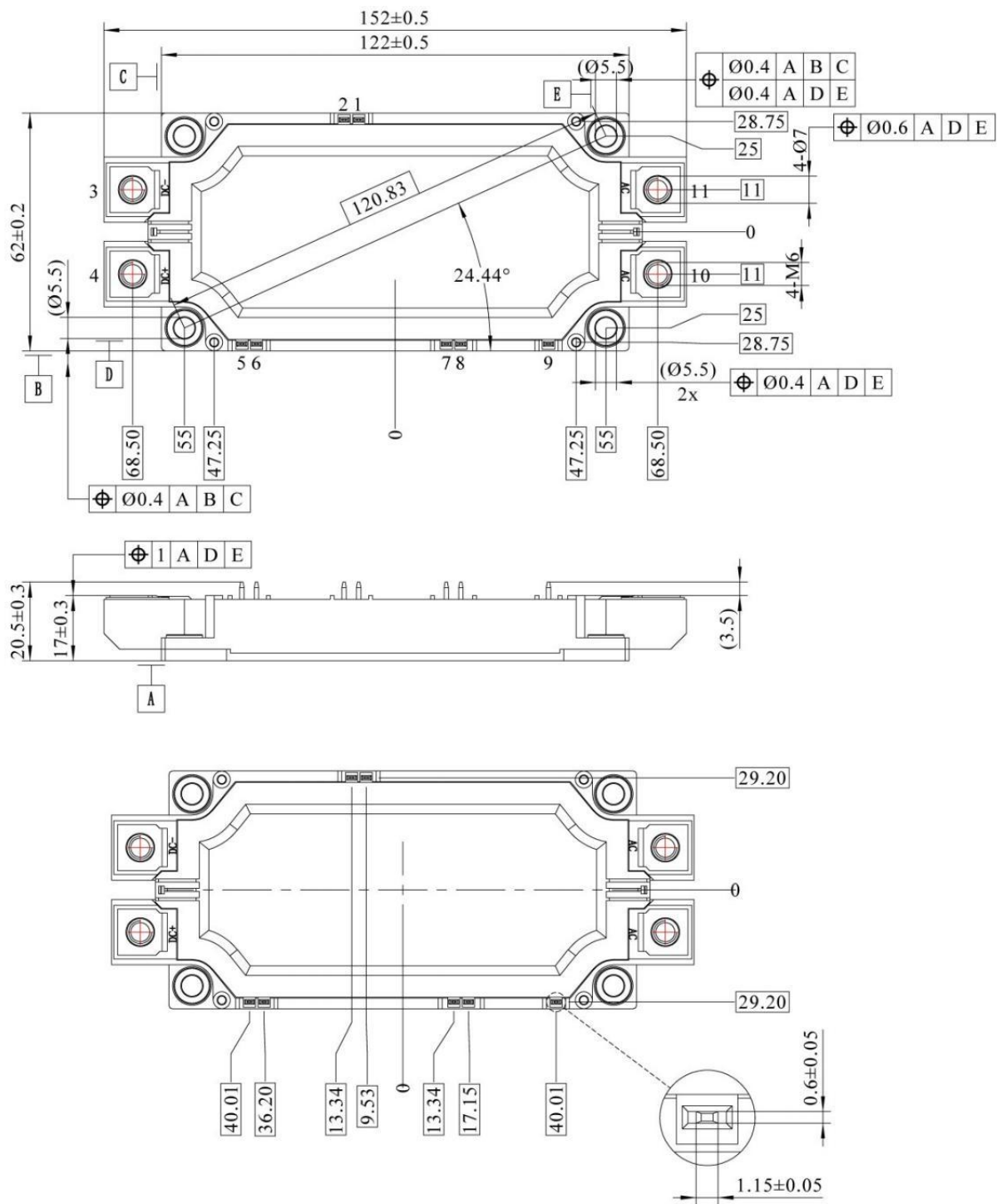


Figure 2. Pin configuration

Module

Parameter	Condition	Value	Unit
Isolation Voltage	RMS, f = 50Hz, t = 1 min	3.4	kV
Material of module baseplate	-	Cu	-
Creepage distance	terminal to heatsink terminal to terminal	14.5 13	mm
Clearance	terminal to heatsink terminal to terminal	12.5 10	mm
CTI	-	600	-
Module lead resistance, terminals - chip	T _C = 25°C	0.8	mΩ
Mounting torque for module mounting	M5, M6	3 to 6	Nm
Weight	-	350	g

Maximum Ratings (T_j = 25°C unless otherwise specified)

Symbol	Parameter	Condition	Ratings	Unit
V _{CES}	Collector-Emitter Voltage	G-E Short	1200	V
V _{GES}	Gate-Emitter Voltage	C-E Short	±20	V
I _C	DC Continuous Collector Current	T _C = 95°C	450	A
I _{CM}	Pulse Collector Current	t _p = 1ms, Note1	900	A
P _C	Maximum Power Dissipation	T _C = 25°C, IGBT	2239	W
I _F	Diode Forward Current	-	450	A
I _{FRM}	Repetitive peak forward Current	t _p = 1ms, Note1	900	A
T _{vjop}	Operating junction temperature	Note2	-40 to 175	°C
T _{stg}	Storage temperature	-	-40 to 125	°C

Note1: Pulse width limited by maximum junction temperature

Note2: T_{vjop} > 150°C is only allowed for operation at overload conditions

NTC characteristics

Symbol	Parameter	Condition	Value			Unit
			Min.	Typ.	Max.	
R ₂₅	Resistance	T _C = 25°C	-	5	-	kΩ
ΔR/R	Deviation of R ₁₀₀	T _C = 100°C, R ₁₀₀ = 493Ω	-5	-	5	%
P ₂₅	Power dissipation	T _C = 25°C	-	-	20	mW
B _{25/50}	B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3375	-	K
B _{25/80}	B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3411	-	K
B _{25/100}	B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3433	-	K

IGBT Electrical characteristics (T_j=25°C unless otherwise specified, chip)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max.	
V _{CE(sat)} (Chip)	Collector-Emitter Saturation Voltage	I _C =450A V _{GE} =15V	T _j =25°C	-	1.60	1.92	V
			T _j =125°C	-	1.73	-	
			T _j =150°C	-	1.80	-	
			T _j =175°C	-	1.85	-	
V _{GE(th)}	Gate-Emitter threshold Voltage	I _C =17mA, V _{CE} =V _{GE}		5.0	5.8	6.5	V
Q _G	Gate charge	V _{GE} = -15V to +15V		-	5.2	-	uC
R _{Gint}	Internal gate resistor	-	T _j =25°C	-	0.7	-	Ω
C _{ies}	Input Capacitance	V _{CE} =25V	T _j =25°C	-	64.8	-	nF
C _{oes}	Output Capacitance	V _{GE} =0V		-	1.76	-	nF
C _{res}	Reverse transfer Capacitance	f=1MHz		-	0.50	-	nF
I _{CES}	Collector- Emitter Cut off Current	V _{CE} =1200V, V _{GE} =0V	T _j =25°C	-	-	1	mA
I _{GES}	Gate-Emitter Leakage Current	V _{GE} = 20V, V _{CE} =0V	T _j =25°C	-	-	1	uA
t _{d(on)}	Turn-on delay time	V _{CC} =600V I _C =450A V _{GE} =+15V/-8V R _G =1.0Ω Inductive load	T _j =25°C	-	254	-	ns
			T _j =125°C	-	262	-	
			T _j =150°C	-	264	-	
t _r	Rise time		T _j =25°C	-	61	-	ns
			T _j =125°C	-	82	-	
			T _j =150°C	-	87	-	
t _{d(off)}	Turn-off delay time		T _j =25°C	-	455	-	ns
			T _j =125°C	-	494	-	
			T _j =150°C	-	504	-	
t _f	Fall time		T _j =25°C	-	194	-	ns
			T _j =125°C	-	292	-	
			T _j =150°C	-	317	-	
				T _j =25°C	-	40.6	-

E _{on}	Turn-on power dissipation		T _j =125°C	-	60.8	-	mJ
			T _j =150°C	-	65.8	-	
E _{off}	Turn-off power dissipation		T _j =25°C	-	37.5	-	mJ
			T _j =125°C	-	48.8	-	
			T _j =150°C	-	51.6	-	
R _{th(j-c)}	Thermal Resistance, Junction to Case (IGBT)			-	0.067	-	°C/W
R _{th(c-s)}	Thermal Resistance, Case to sink (Conductive Grease applied) , Note1			-	0.020	-	°C/W

Note1: Assumes Thermal Conductivity of grease is 2.8 W/m · K and thickness is 50um

Freewheeling Diode Electrical characteristics ($T_j=25^\circ\text{C}$ unless otherwise specified, chip)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max.	
V _F (Chip)	Diode Forward Voltage	I _F =450A, V _{GE} =0V	T _j =25°C	-	1.64	1.97	V
			T _j =125°C	-	1.48	-	
			T _j =150°C	-	1.49	-	
			T _j =175 °C	-	1.44	-	
t _{rr}	Reverse recovery time	(Switch side) V _{CC} =600V I _C =450A	T _j =25°C	-	0.620	-	us
			T _j =125°C	-	0.673	-	
			T _j =150°C	-	0.687	-	
I _{RM}	Peak reverse recovery Current	V _{GE} =+15V/-8V R _G =1.0Ω (FRD side) V _{rr} =600V	T _j =25°C	-	353	-	A
			T _j =125°C	-	383	-	
			T _j =150°C	-	390	-	
Q _{rr}	Recovered charge	I _F =450A V _{GE} =-8V Inductive load switching operation	T _j =25°C	-	89.9	-	uC
			T _j =125°C	-	135.5	-	
			T _j =150°C	-	147.0	-	
E _{rr}	Reverse recovered energy		T _j =25°C	-	40.3	-	mJ
			T _j =125°C	-	58.9	-	
			T _j =150°C	-	63.5	-	
R _{th(j-c)}	Thermal Resistance, Junction to Case (Diode)			-	0.093	-	°C/W
R _{th(c-s)}	Thermal Resistance, Case to sink (Conductive Grease applied) , Note1			-	0.025	-	°C/W

Note1: Assumes Thermal Conductivity of grease is $2.8 \text{ W/m} \cdot \text{K}$ and thickness is $50\mu\text{m}$

Test Conditions

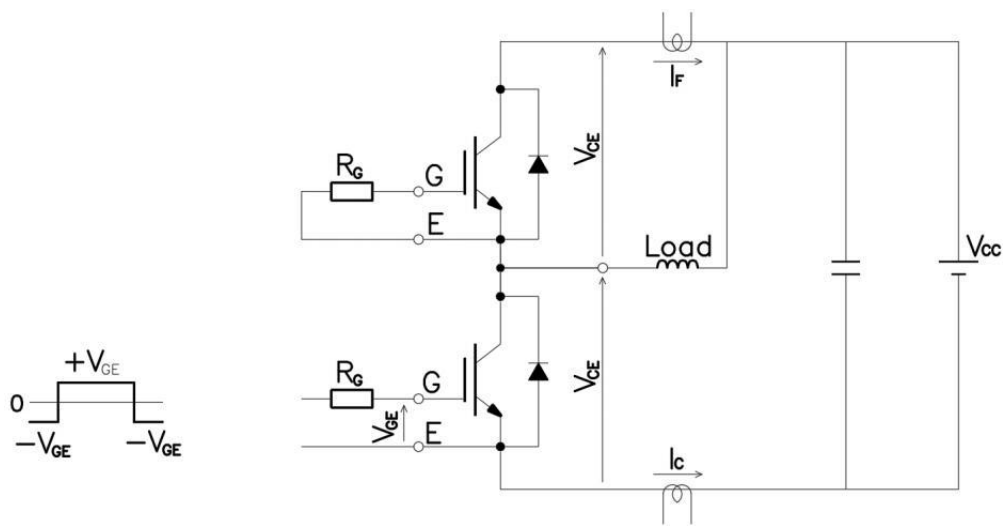


Figure 3. Switching time measure circuit

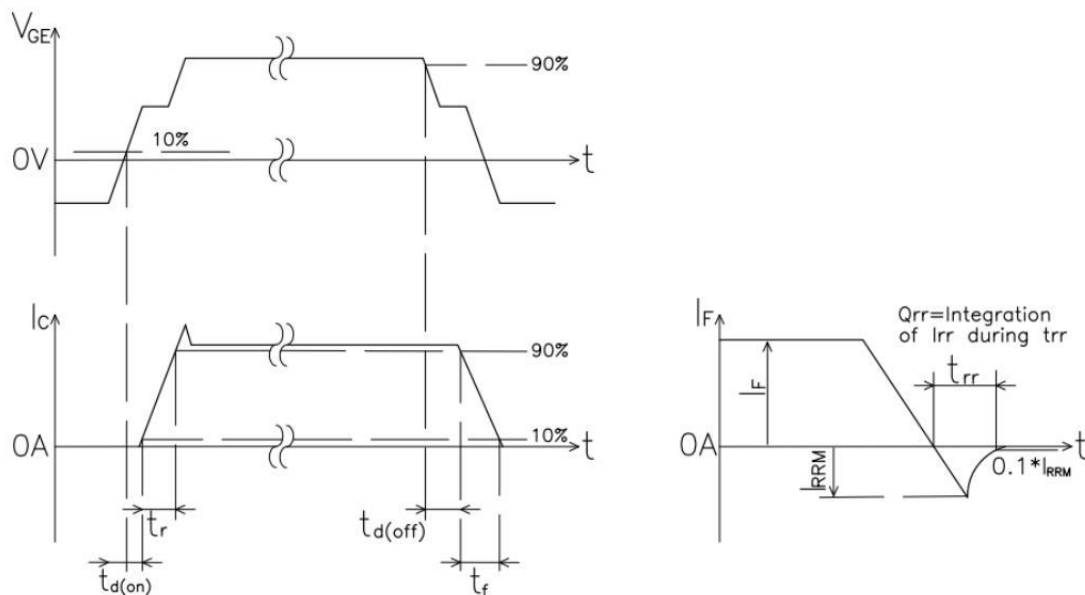
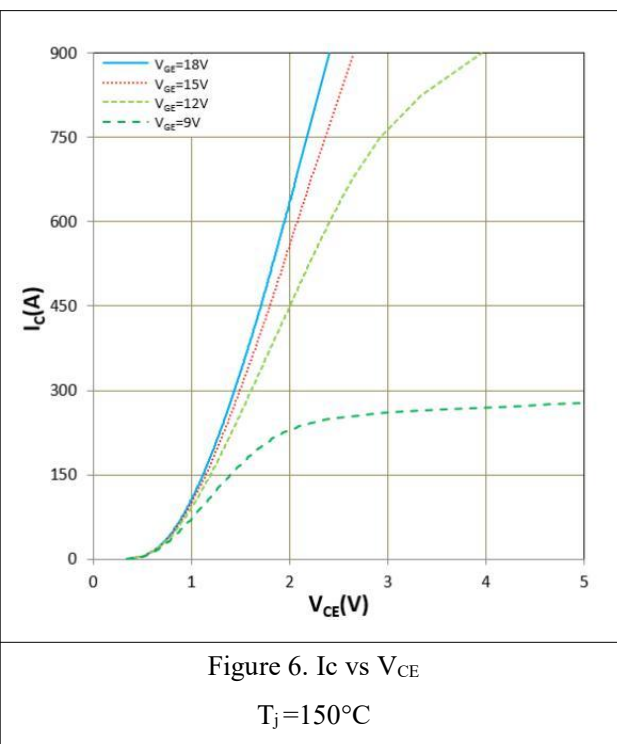
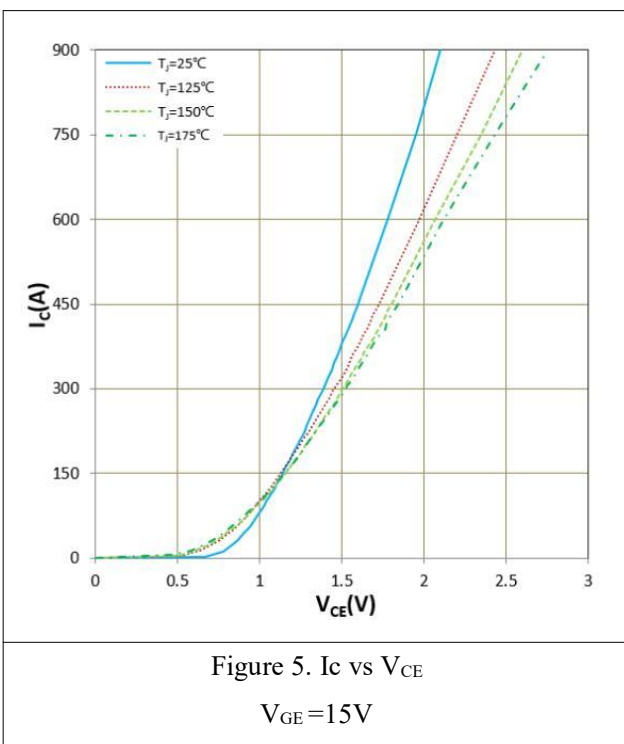


Figure 4. Switching time definition



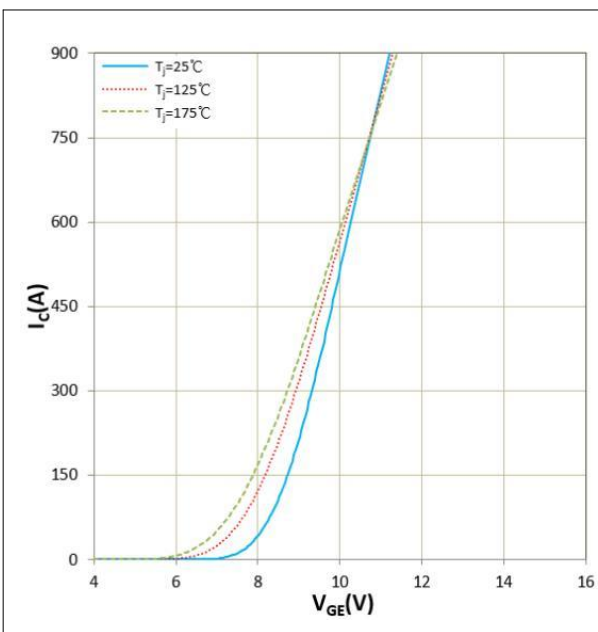


Figure 7. I_C vs V_{GE}

$V_{CE} = 20\text{V}$

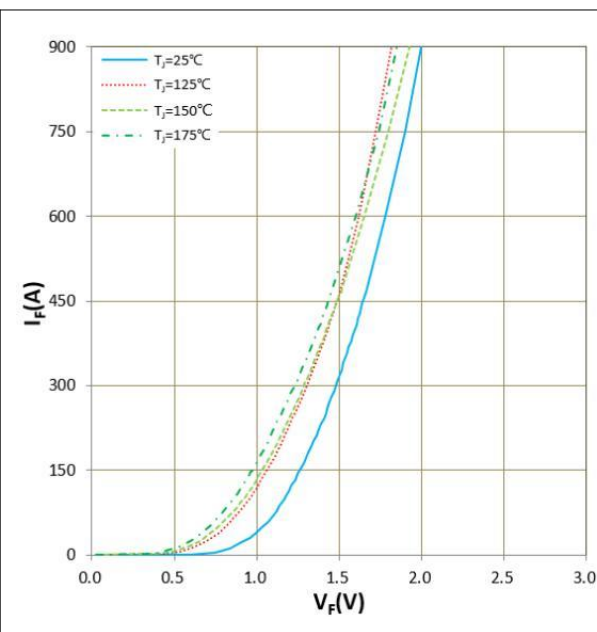


Figure 8. I_F vs V_F

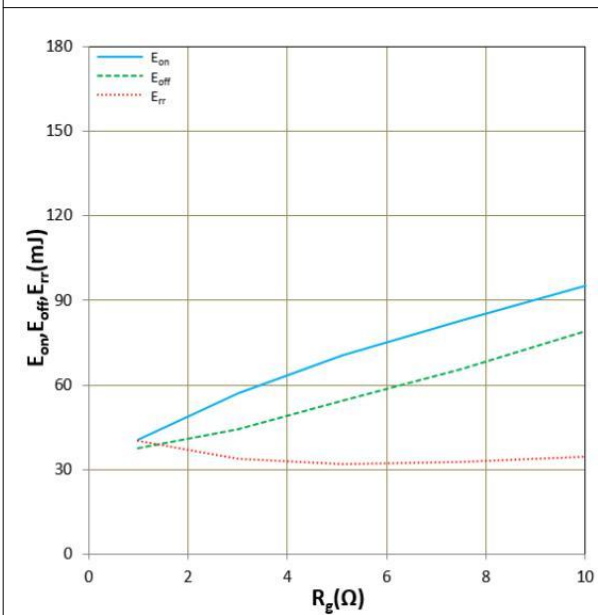


Figure 9. E_{on} , E_{off} , E_{rr} vs R_g (Typ)

$V_{CC} = 600\text{V}$, $V_{GE} = +15\text{V}/-8\text{V}$, $I_C = 450\text{A}$, $T_J = 25^\circ\text{C}$

Inductive Load

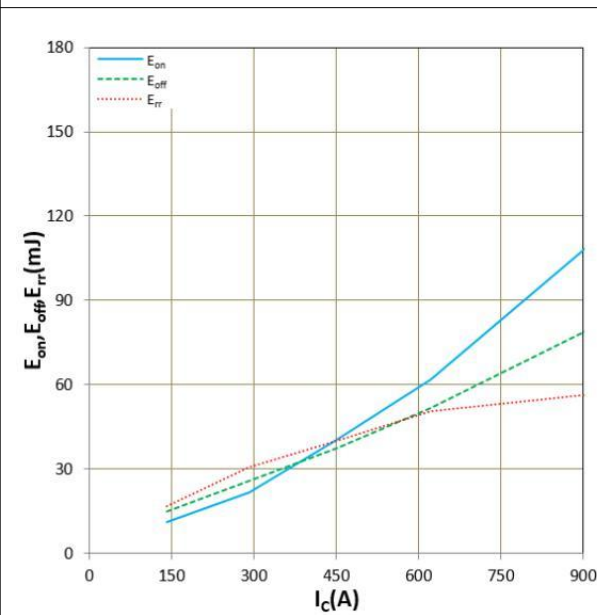


Figure 10. E_{on} , E_{off} , E_{rr} vs I_C (Typ)

$V_{CC} = 600\text{V}$, $V_{GE} = +15\text{V}/-8\text{V}$, $R_g = 1.0\Omega$, $T_J = 25^\circ\text{C}$

Inductive Load

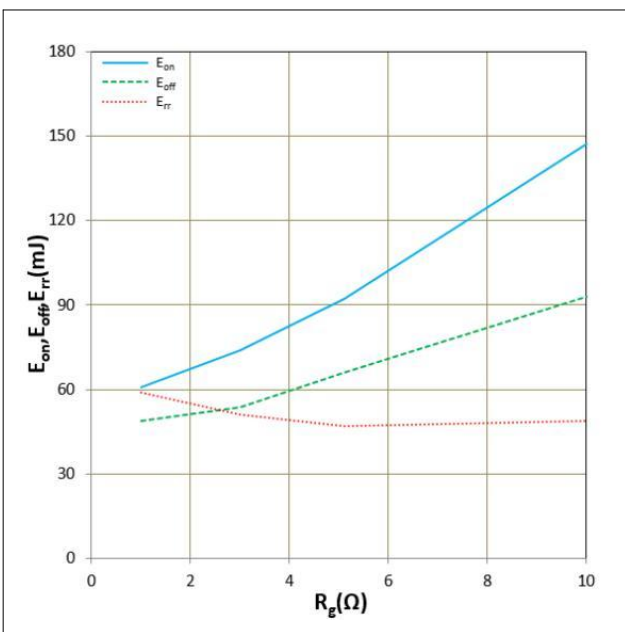


Figure 11. E_{on} , E_{off} , E_{rr} vs R_g (Typ)

$V_{CC}=600V$, $V_{GE}=+15V/-8V$, $I_C=450A$, $T_j=125^\circ C$

Inductive Load

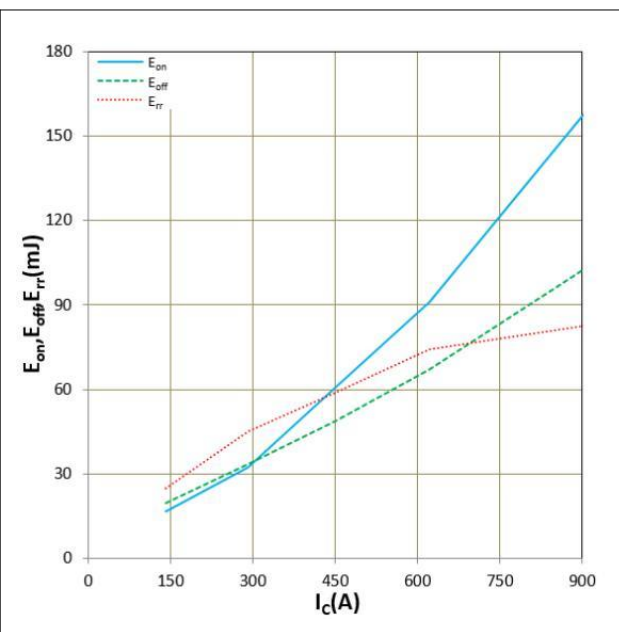


Figure 12. E_{on} , E_{off} , E_{rr} vs I_C (Typ)

$V_{CC}=600V$, $V_{GE}=+15V/-8V$, $R_g=1.0\Omega$, $T_j=125^\circ C$

Inductive Load

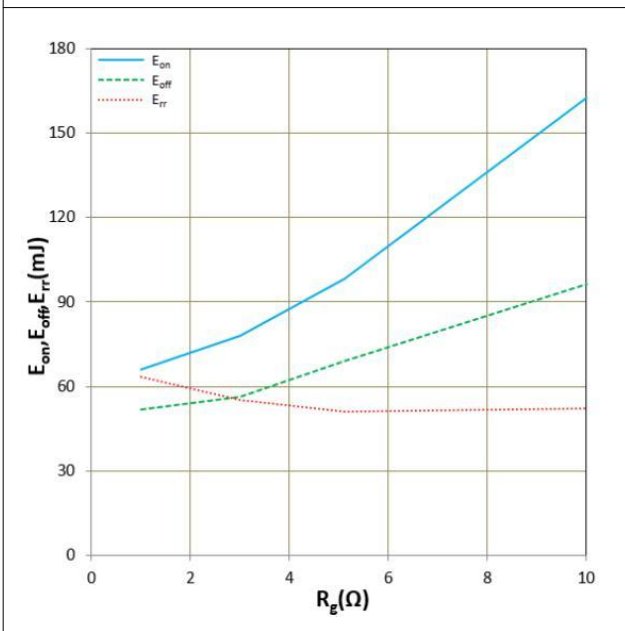


Figure 13. E_{on} , E_{off} , E_{rr} vs R_g (Typ)

$V_{CC}=600V$, $V_{GE}=+15V/-8V$, $I_C=450A$, $T_j=150^\circ C$

Inductive Load

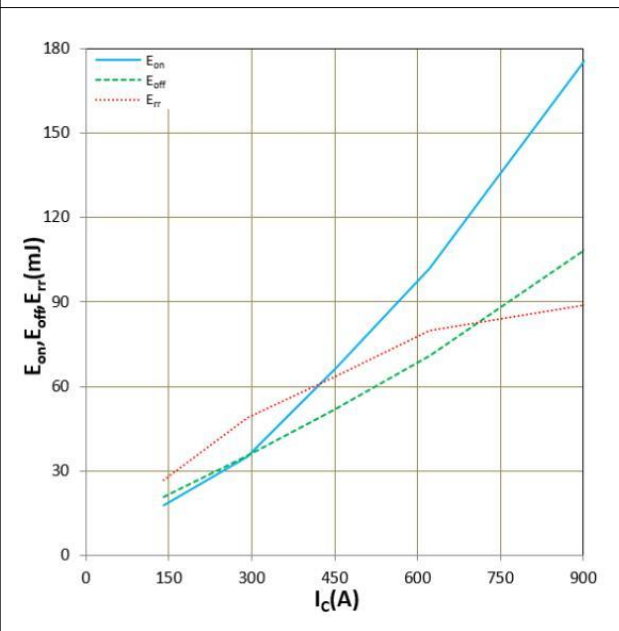


Figure 14. E_{on} , E_{off} , E_{rr} vs I_C (Typ)

$V_{CC}=600V$, $V_{GE}=+15V/-8V$, $R_g=1.0\Omega$, $T_j=150^\circ C$

Inductive Load

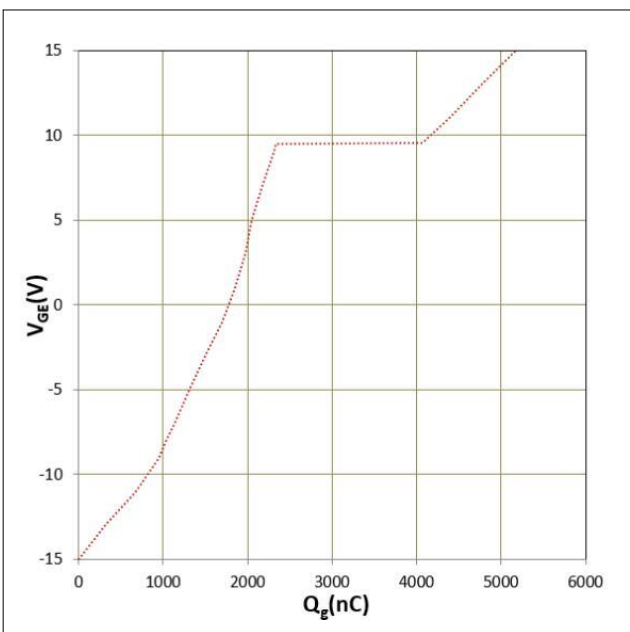


Figure 15. Gate charge

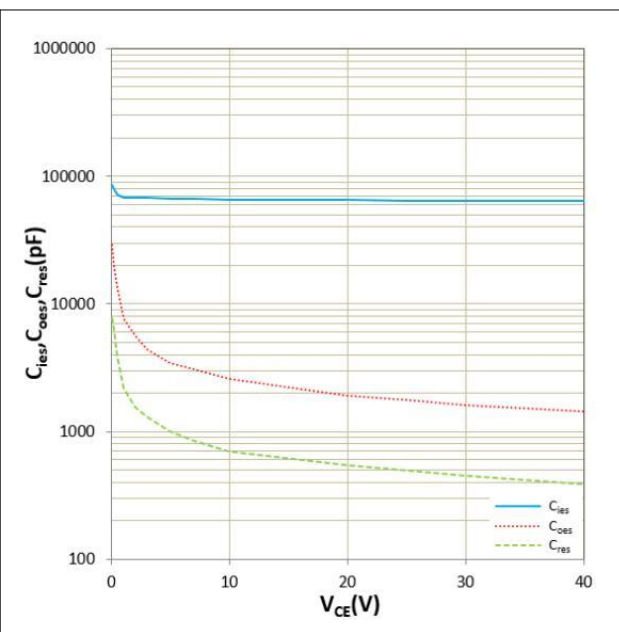


Figure 16. C_{ies} , C_{oes} , C_{res} vs V_{CE}
 $T_j = 25^\circ\text{C}$, $f = 1\text{MHz}$

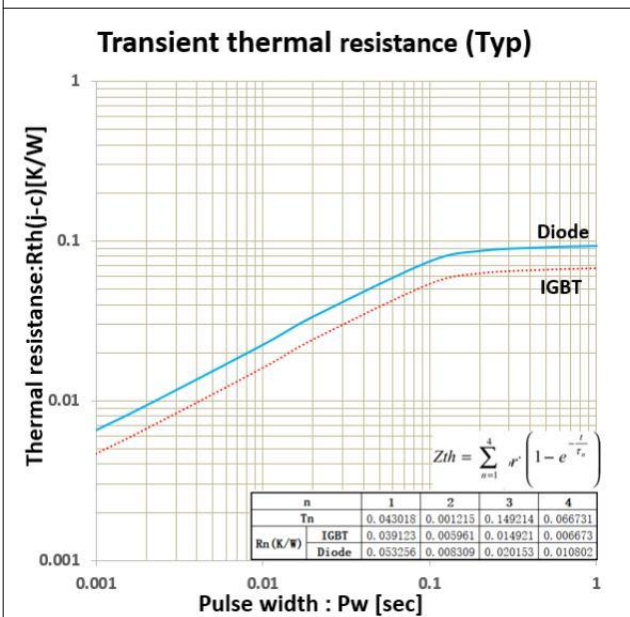


Figure 17. transient thermal impedance
IGBT/Diode

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